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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/815,561	03/31/2004	Paul A. Koning	884.C15US1	7131	
7590 02/24/2005 Schwegman, Lundberg, Woessner & Kluth, P.A. P.O. Box 2938			EXAM	EXAMINER	
			GURLEY, LYNNE ANN		
Minneapolis, MN 55402			ART UNIT	PAPER NUMBER	
•			2812		
			DATE MAILED: 02/24/2005	5	

Please find below and/or attached an Office communication concerning this application or proceeding.

				H'F			
		Application No.	Applicant(s)				
Office Action Summary		10/815,561	KONING, PAUL A				
		Examiner	Art Unit				
		Lynne A. Gurley	2812				
Period f	The MAILING DATE of this communication or Reply	n appears on the cover shee	et with the correspondence address -				
THE - Extrafte - If th - If N - Fail	HORTENED STATUTORY PERIOD FOR R MAILING DATE OF THIS COMMUNICATI ensions of time may be available under the provisions of 37 C r SIX (6) MONTHS from the mailing date of this communicatic e period for reply specified above is less than thirty (30) days, O period for reply is specified above, the maximum statutory pure to reply within the set or extended period for reply will, by reply received by the Office later than three months after the ned patent term adjustment. See 37 CFR 1.704(b).	ON. FR 1.136(a). In no event, however, mon. a reply within the statutory minimum operiod will apply and will expire SIX (6) statute, cause the application to become	ay a reply be timely filed of thirty (30) days will be considered timely. MONTHS from the mailing date of this communication (25 U.S.C. § 133).	ation.			
Status							
1)⊠	Responsive to communication(s) filed on	29 November 2004.					
		This action is non-final.					
3)[Since this application is in condition for allowance except for formal matters, prosecution as to the merits is						
	closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.						
Disposi	tion of Claims						
4)⊠	Claim(s) <u>1-26 and 30-32</u> is/are pending in 4a) Of the above claim(s) is/are wit						
5)[Claim(s) is/are allowed.						
6)⊠	☑ Claim(s) <u>1-26 and 30-32</u> is/are rejected.						
· —	')□ Claim(s) is/are objected to.						
8)∐	Claim(s) are subject to restriction a	and/or election requirement					
Applica	tion Papers						
9)[The specification is objected to by the Exa	miner.					
10)	10)☐ The drawing(s) filed on is/are: a)☐ accepted or b)☐ objected to by the Examiner.						
	Applicant may not request that any objection to	o the drawing(s) be held in ab	eyance. See 37 CFR 1.85(a).				
_	Replacement drawing sheet(s) including the o	•	• • •	` ,			
11)	The oath or declaration is objected to by the	ne Examiner. Note the atta	ched Office Action or form PTO-152	2.			
Priority	under 35 U.S.C. § 119						
	Acknowledgment is made of a claim for fo All b) Some * c) None of: 1. Certified copies of the priority documents.						
	2. Certified copies of the priority docu	ments have been received	in Application No				
	 Copies of the certified copies of the application from the International B 		een received in this National Stage	•			
*	See the attached detailed Office action for	, , , , , , , , , , , , , , , , , , , ,	not received. Jane Holy	_			
			LYNNE A. GURLEY	EB			
			PRIMARY PATENT EXĂMINI TC 2800, AU 2812	m#1			
Attachme	* *						
	ce of References Cited (PTO-892) ce of Draftsperson's Patent Drawing Review (PTO-94		iew Summary (PTO-413) No(s)/Mail Date				
	ce of Draftsperson's Patent Drawing Review (PTO-94) rmation Disclosure Statement(s) (PTO-1449 or PTO/S	·	e of Informal Patent Application (PTO-152)				
	er No(s)/Mail Date		:·				

DETAILED ACTION

This Office Action is in response to the election/response, filed 11/29/04.

Currently, claims 1-26 and 30-32 are pending.

Election/Restrictions

- 1. Applicant's election without traverse of claims 1-26 and 30-32 in the reply filed on 11/29/04 is acknowledged.
- 2. Claims 27-29 have been withdrawn from further consideration pursuant to 37 CFR 1.142(b) as being drawn to a nonelected invention, there being no allowable generic or linking claim. Election was made without traverse in the reply filed on 11/29/04. Additionally, it is noted that claims 27-29 have been canceled by Applicant.

Specification

3. The lengthy specification has not been checked to the extent necessary to determine the presence of all possible minor errors. Applicant's cooperation is requested in correcting any errors of which applicant may become aware in the specification.

Claim Rejections - 35 USC § 103

- 4. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

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5. The factual inquiries set forth in *Graham* v. *John Deere Co.*, 383 U.S. 1, 148 USPQ 459 (1966), that are applied for establishing a background for determining obviousness under 35 U.S.C. 103(a) are summarized as follows:

- 1. Determining the scope and contents of the prior art.
- 2. Ascertaining the differences between the prior art and the claims at issue.
- 3. Resolving the level of ordinary skill in the pertinent art.
- 4. Considering objective evidence present in the application indicating obviousness or nonobviousness.
- 6. Claims 1-26 and 30-32 are rejected under 35 U.S.C. 103(a) as being unpatentable over Chen et al. (US 6,756,294, dated 6/29/04, filed 1/30/02) in view of Brewer (US 2004/0142575, dated 7/22/04, filed 7/25/03).

Chen shows the method substantially as claimed, in figures 1-14 and corresponding text, with emphasis on figures 5-12, as forming a polymer 12 (polyimide passivation layer) disposed upon a substrate 10 under conditions to expose a bond pad 14 on the substrate, wherein a recess is formed in the polymer (fig. 5); mating a solder bump 41 (fig. 41) with the bond pad; and curing the polymer (column 6, lines 25-27). The solder bump is reflowed and solder flux is used (column 4, lines 11-15). A convex over-all profile or, contoured recess is formed in the polymer. Multiple layers of polyimide can be used for the passivation layer (column 5, lines 59-67; column 6, lines 1-46).

Chen lacks anticipation only in not teaching: forming an imprinted polymer disposed upon the substrate under conditions to expose the bond pad on the substrate by local flow of the polymer; a microprocessor mated with the solder bump, wherein mating includes at least partially flattening the convex over-all profile; wherein mating the solder bump with the bond

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pad includes mating a complementary-contoured solder bump in the recess; the film-to-substrate thickness ratio; the specifics of the polymer composition with resin and filler and pre-polymer.

Brewer teaches a method of imprinting a polymer on a substrate, with emphasis on figures 4A-4D and corresponding text [1165]-[0075]. The polymer is imprinted using a stamp for efficiency. Epoxies and resins are discussed as polymers on silicon wafers. Curing the polymer after imprinting is discussed [0075] to harden the polymer. These patterning techniques may be used for a variety of devices, which require the patterning of a polyimide layer.

It would have been obvious to one of ordinary skill in the art to have formed an imprinted polymer disposed upon the substrate under conditions to expose the bond pad on the substrate by local flow of the polymer, to have had a microprocessor mated with the solder bump, wherein mating includes at least partially flattening the convex over-all profile; to have had the method comprise the steps wherein mating the solder bump with the bond pad includes mating a complementary-contoured solder bump in the recess; to have had the claimed film-to-substrate thickness ratio; and to have had the claimed specifics of the polymer composition with resin and filler and pre-polymer, in the method of Chen, with the motivation that Brewer teaches a method of patterning the polymer passivation layers for a large area of IC devices. Therefore, using the imprinting technique taught by Brewer would make the patterning process of Chen more efficient. The Examiner notes that the resins and pre-polymer materials and epoxys, as well as the filler are conventional in the art when considering the use of polymers, as would be the reflow of the polymer. The microprocessor and the complementary-countoured solder bump would be obvious to one of ordinary skill in the art to have incorporated depending on the

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purpose of the device as a whole. Additionally, had the claimed film-to-substrate thickness ratio would have been reasonable to one of ordinary skill in the art.

Conclusion

7. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. See the PTO Form 892.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Lynne A. Gurley whose telephone number is 571-272-1670. The examiner can normally be reached on M-F 7:30-4:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Michael Lebentritt can be reached on 571-272-1873. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Lynne A. Gurley

Primary Patent Examiner

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LAG February 22, 2005